

IN THE CLAIMS:

Please amend the claims as follows:

1. (Original) A fluid processing cell configured to control the temperature of a substrate during processing, comprising:
 - a substrate support assembly positioned in a processing volume;
 - a disk shaped member positioned in the processing volume in parallel orientation with a substrate supported on the substrate support assembly;
 - a fluid outlet positioned in a central location of the disk shaped member; and
 - a plurality of turbolators positioned on an upper surface of the disk shaped member, the turbolators being configured to generate a uniform turbulent flow of fluid traveling from the fluid outlet to a perimeter of the substrate.
2. (Original) The fluid processing cell of claim 1, wherein the turbolators comprise arc shaped members positioned radially around the fluid outlet.
3. (Original) The fluid processing cell of claim 2, wherein the turbolators are positioned in concentric annular rings around the fluid outlet.
4. (Original) The fluid processing cell of claim 3, wherein the turbolators in an inner ring define a fluid passage therebetween, the fluid passage being in alignment with a turbolator in an outer ring.
5. (Original) The fluid processing cell of claim 1, further comprising a plurality of fluid dispensing holes positioned adjacent the plurality of turbolators.
6. (Original) The fluid processing cell of claim 1, wherein the turbolators extend vertically from the upper surface a distance of between about 1 mm and about 4 mm.

7. (Original) The fluid processing cell of claim 4, wherein the arc shaped members comprise between about 4 and about 6 arc shaped members per annular ring.
8. (Original) The fluid processing cell of claim 1, wherein the substrate support assembly is configured to support the substrate at a position that is between about 3 mm about 5 mm from the disk shaped member.
9. (Original) The fluid processing cell of claim 1, wherein the fluid outlet is in communication with a source of heated fluid.
10. (Currently Amended) An electroless deposition cell for semiconductor substrates, comprising:
- a substrate support assembly positioned in a cell body;
 - a fluid distribution member in parallel relationship with a substrate positioned on the substrate support assembly;
 - a plurality of turbulators positioned on the fluid distribution member;
 - a fluid delivery aperture formed into a central portion of the fluid distribution member and configured to dispense a heating fluid onto a backside of the substrate, wherein the plurality of turbulators are configured to generate a uniform turbulent flow of fluid traveling from the fluid delivery aperture to a perimeter of the fluid distribution member;
 - an electroless fluid dispensing member positioned to dispense an electroless processing solution onto a frontside of the substrate; and
 - a source of heated fluid in fluid communication with the fluid delivery aperture.
11. (Original) The electroless deposition cell of claim 10, wherein the plurality of turbulators comprise arc shaped members positioned end to end with a fluid space therebetween in a circular pattern around the fluid delivery aperture.

12. (Original) The electroless deposition cell of claim 11, further comprising at least two concentric circular patterns of turbolators.
13. (Original) The electroless deposition cell of claim 12, wherein the turbolators have a height from the distribution member of between about 1 mm and about 3 mm.
14. (Original) The electroless deposition cell of claim 13, wherein the substrate support assembly is configured to support the substrate at a distance of between about 3 mm and about 5mm from the fluid distribution assembly.
15. (Original) The electroless deposition cell of claim 12, wherein the fluid space of the inner ring is positioned radially inward of a turbolator of an outer ring.
16. (Original) The electroless deposition cell of claim 12, further comprising a plurality of fluid distribution apertures formed into an upper surface of the fluid distribution member proximate the turbolators.
17. (Withdrawn) An electroless deposition method, comprising:
positioning a substrate face up on a substrate support member;
positioning a fluid distribution member below a backside of the substrate, the fluid distribution member having a central fluid dispensing aperture formed therein and a plurality of fluid turbolators positioned thereon;
dispensing an electroless processing solution onto a production surface of the substrate;
dispensing a heated fluid into a space between the backside of the substrate and the fluid distribution member via the central fluid dispensing aperture while the electroless processing solution is dispensed onto the production surface; and
generating a turbulent uniform outward flow of the heated fluid across the backside of the substrate by passing the heated fluid over the turbolators.

18. (Withdrawn) The method of claim 17, wherein generating the turbulent flow comprises flowing the heated fluid over turbolators having a height of between about 1 mm and about 4 mm.
19. (Withdrawn) The method of claim 18, wherein generating the turbulent flow comprises flowing the heated fluid over arc shaped turbolators positioned in an annular pattern with fluid passage spaces separating ends of the arcs.
20. (Withdrawn) The method of claim 19, wherein generating the turbulent flow comprises flowing the heated fluid over at least two concentric rings of turbolators positioned radially around central fluid dispensing aperture.
21. (Withdrawn) The method of claim 20, further comprising dispensing the heated fluid from a plurality of fluid dispensing apertures positioned adjacent each of the turbolators.
22. (Withdrawn) The method of claim 17, wherein the backside of the substrate is spaced from the fluid distribution member by between about 3 mm and about 6 mm.